CSD19536KTT 100-V N-Channel NexFET™ Power MOSFET

1 Features

- Ultra-Low Q_g and Q_{gd}
- Low Thermal Resistance
- Avalanche Rated
- Lead-Free Terminal Plating
- RoHS Compliant
- Halogen Free
- D^2PAK Plastic Package

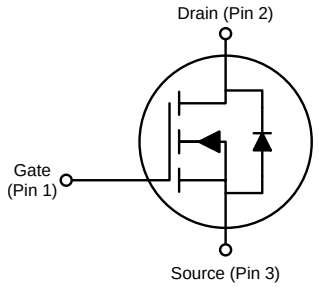
2 Applications

- Secondary Side Synchronous Rectifier
- Hot Swap
- Motor Control

3 Description

This 100-V, 2-mΩ, D^2PAK (TO-263) NexFET™ power MOSFET is designed to minimize losses in power conversion applications.

Pin Out



Product Summary

T_A = 25°C		TYPICAL VALUE		UNIT
V_{DS}	Drain-to-Source Voltage	100		V
Q_g	Gate Charge Total (10 V)	118		nC
Q_{gd}	Gate Charge Gate-to-Drain	17		nC
$R_{DS(on)}$	Drain-to-Source On-Resistance	V_{GS} = 6 V	2.2	mΩ
		V_{GS} = 10 V	2	
$V_{GS(th)}$	Threshold Voltage	2.5		V

Device Information(1)

DEVICE	QTY	MEDIA	PACKAGE	SHIP
CSD19536KTT	500	13-Inch Reel	D^2PAK Plastic Package	Tape and Reel
CSD19536KTTT	50			

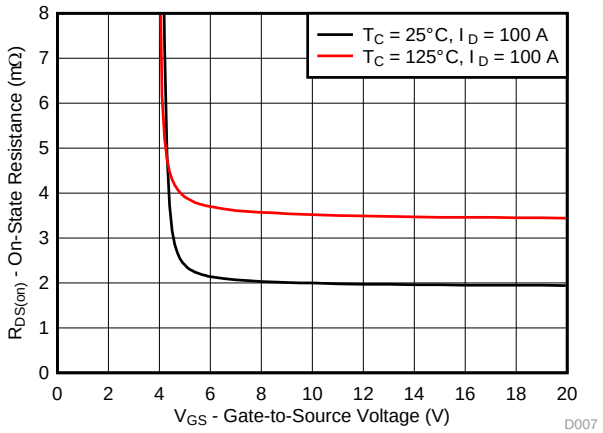
(1) For all available packages, see the orderable addendum at the end of the data sheet.

Absolute Maximum Ratings

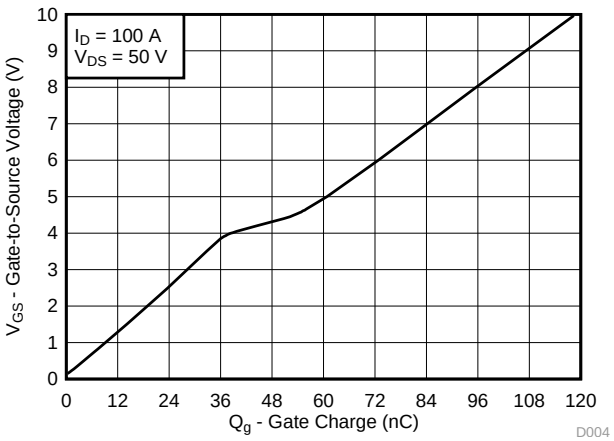
T_A = 25°C		VALUE	UNIT
V_{DS}	Drain-to-Source Voltage	100	V
V_{GS}	Gate-to-Source Voltage	±20	V
I_D	Continuous Drain Current (Package Limited)	200	A
	Continuous Drain Current (Silicon Limited), T_C = 25°C	272	
	Continuous Drain Current (Silicon Limited), T_C = 100°C	192	
I_{DM}	Pulsed Drain Current(1)	400	A
P_D	Power Dissipation	375	W
T_J, T_{stg}	Operating Junction, Storage Temperature	–55 to 175	°C
E_{AS}	Avalanche Energy, Single Pulse I_D = 127 A, L = 0.1 mH, R_G = 25 Ω	806	mJ

(1) Max $R_{\theta JC}$ = 0.4°C/W, Pulse duration ≤ 100 µs, Duty cycle ≤ 1%.

$R_{DS(on)}$ vs V_{GS}



Gate Charge



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4 Revision History

Changes from Revision A (May 2015) to Revision B **Page**

- Added *Receiving Notification of Documentation Updates* section 7
- Updated package drawing 8
- Updated PCB drawing 9
- Updated stencil drawing 10

Changes from Original (March 2015) to Revision A **Page**

- Added *Community Resources* section 7
- Added PCB and stencil drawings in *Mechanical, Packaging, and Orderable Information* 8

5 Specifications

5.1 Electrical Characteristics

T_A = 25°C (unless otherwise stated)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
STATIC CHARACTERISTICS						
BV_{DSS}	Drain-to-source voltage	V_{GS} = 0 V, I_D = 250 μA	100			V
I_{DSS}	Drain-to-source leakage current	V_{GS} = 0 V, V_{DS} = 80 V			1	μA
I_{GSS}	Gate-to-source leakage current	V_{DS} = 0 V, V_{GS} = 20 V			100	nA
$V_{GS(th)}$	Gate-to-source threshold voltage	V_{DS} = V_{GS}, I_D = 250 μA	2.1	2.5	3.2	V
$R_{DS(on)}$	Drain-to-source on-resistance	V_{GS} = 6 V, I_D = 100 A		2.2	2.8	mΩ
		V_{GS} = 10 V, I_D = 100 A		2	2.4	
g_{fs}	Transconductance	V_{DS} = 10 V, I_D = 100 A		329		S
DYNAMIC CHARACTERISTICS						
C_{iss}	Input capacitance	V_{GS} = 0 V, V_{DS} = 50 V, f = 1 MHz		9250	12000	pF
C_{oss}	Output capacitance			1820	2370	pF
C_{rss}	Reverse transfer capacitance			47	61	pF
R_G	Series gate resistance			1.4	2.8	Ω
Q_g	Gate charge total (10 V)	V_{DS} = 50 V, I_D = 100 A		118	153	nC
Q_{gd}	Gate charge gate-to-drain			17		nC
Q_{gs}	Gate charge gate-to-source			37		nC
$Q_{g(th)}$	Gate charge at V_{th}			24		nC
Q_{oss}	Output charge	V_{DS} = 50 V, V_{GS} = 0 V		335		nC
$t_{d(on)}$	Turnon delay time	V_{DS} = 50 V, V_{GS} = 10 V, I_{DS} = 100 A, R_G = 0 Ω		13		ns
t_r	Rise time			8		ns
$t_{d(off)}$	Turnoff delay time			32		ns
t_f	Fall time			6		ns
DIODE CHARACTERISTICS						
V_{SD}	Diode forward voltage	I_{SD} = 100 A, V_{GS} = 0 V		0.9	1.1	V
Q_{rr}	Reverse recovery charge	V_{DS}= 50 V, I_F = 100 A, di/dt = 300 A/μs		548		nC
t_{rr}	Reverse recovery time			103		ns

5.2 Thermal Information

T_A = 25°C (unless otherwise stated)

THERMAL METRIC		MIN	TYP	MAX	UNIT
$R_{\theta JC}$	Junction-to-case thermal resistance			0.4	°C/W
$R_{\theta JA}$	Junction-to-ambient thermal resistance			62	°C/W

5.3 Typical MOSFET Characteristics

T_A = 25°C (unless otherwise stated)

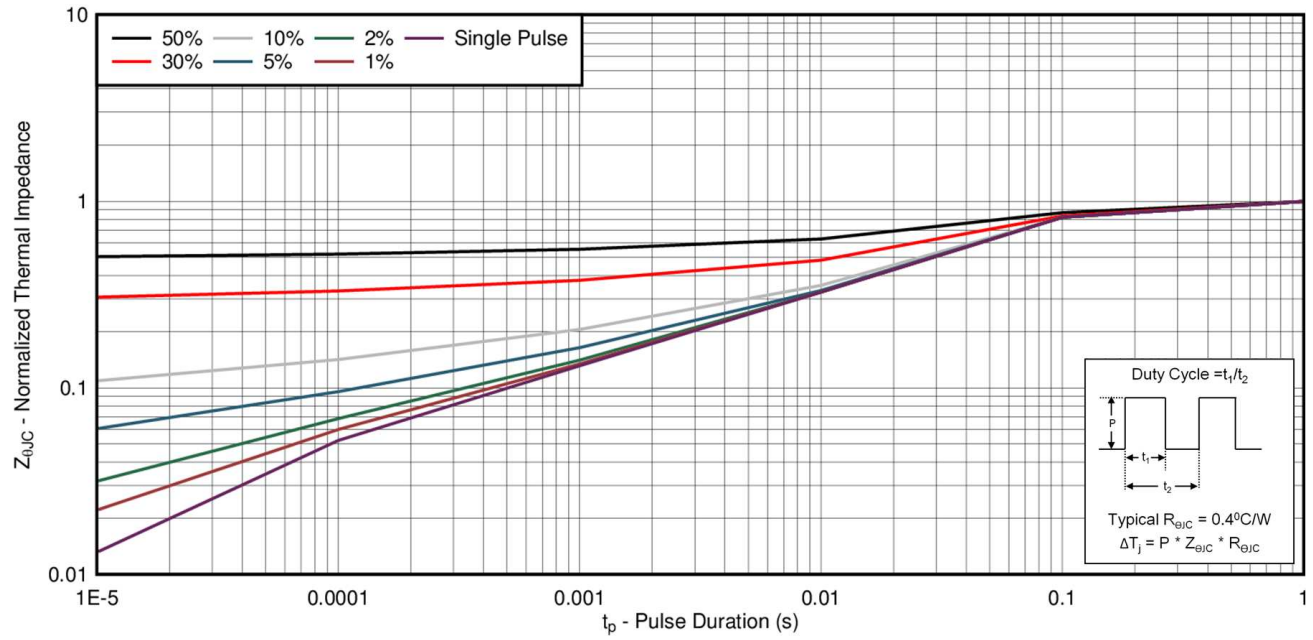

Figure 1. Transient Thermal Impedance

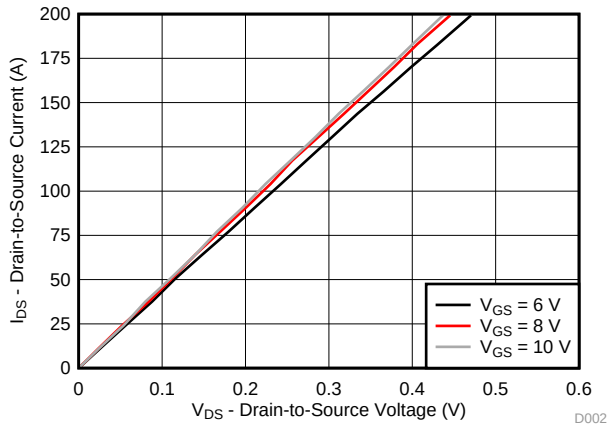

Figure 2. Saturation Characteristics

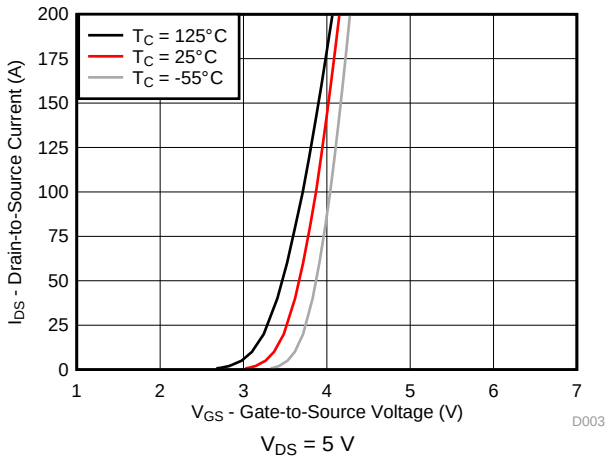

Figure 3. Transfer Characteristics

Typical MOSFET Characteristics (continued)

T_A = 25°C (unless otherwise stated)

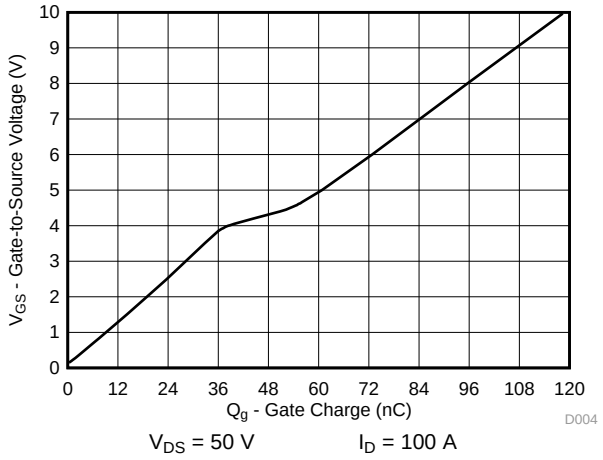

Figure 4. Gate Charge

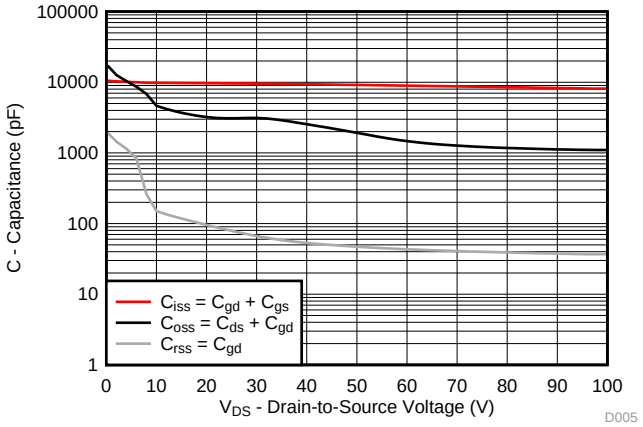

Figure 5. Capacitance

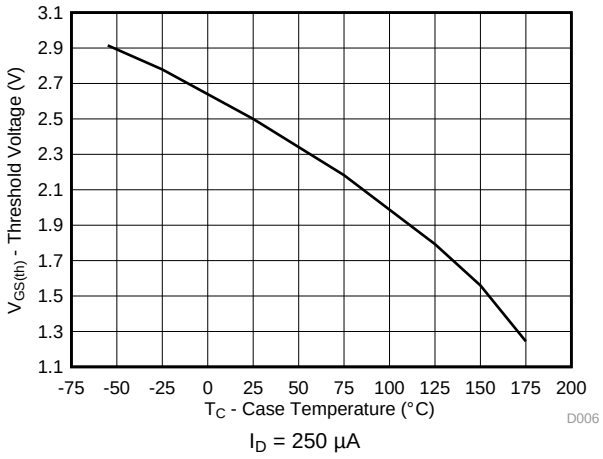

Figure 6. Threshold Voltage vs Temperature

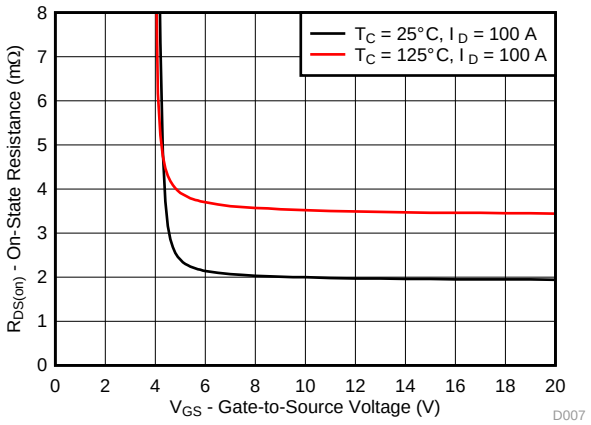

Figure 7. On-State Resistance vs Gate-to-Source Voltage

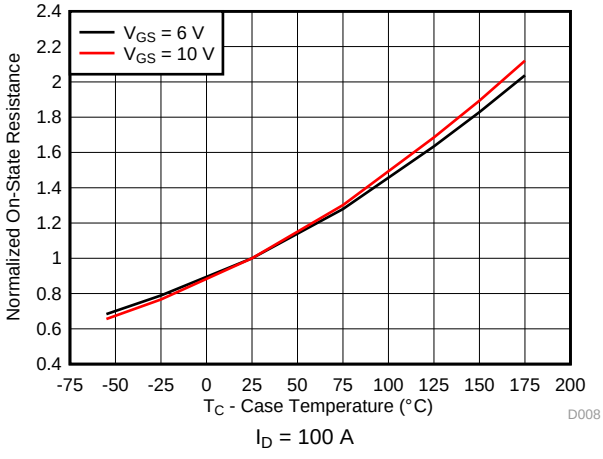

Figure 8. Normalized On-State Resistance vs Temperature

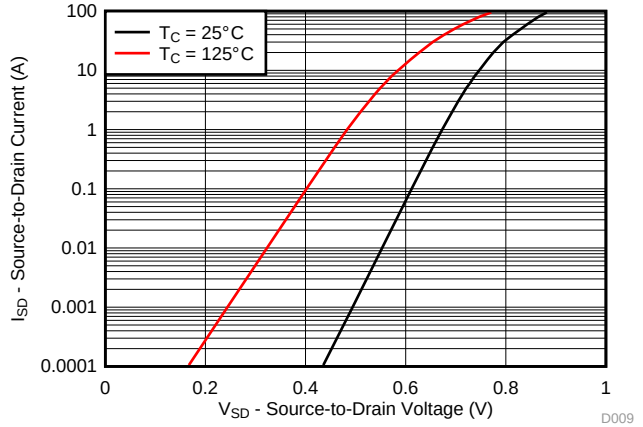

Figure 9. Typical Diode Forward Voltage

Typical MOSFET Characteristics (continued)

T_A = 25°C (unless otherwise stated)

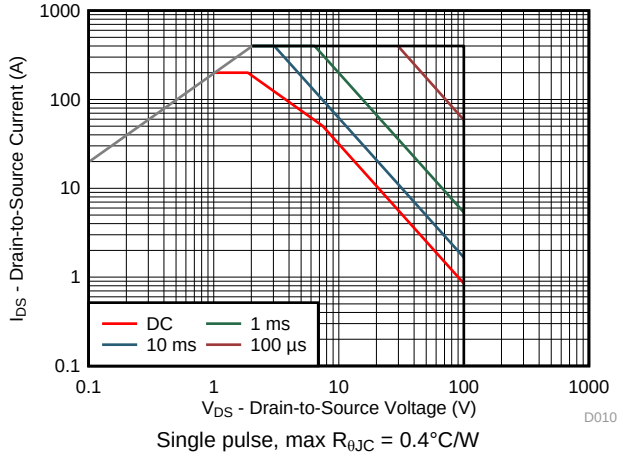

Figure 10. Maximum Safe Operating Area

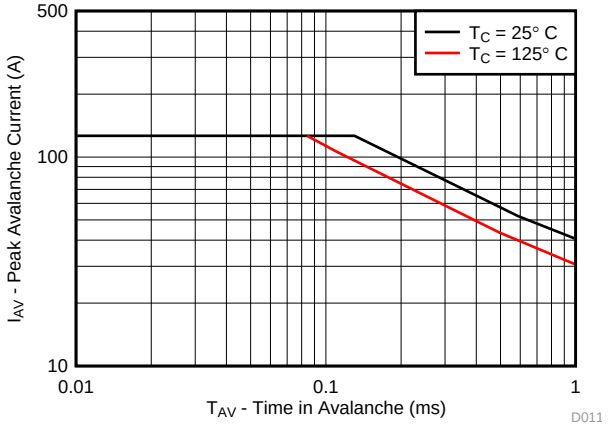

Figure 11. Single Pulse Unclamped Inductive Switching

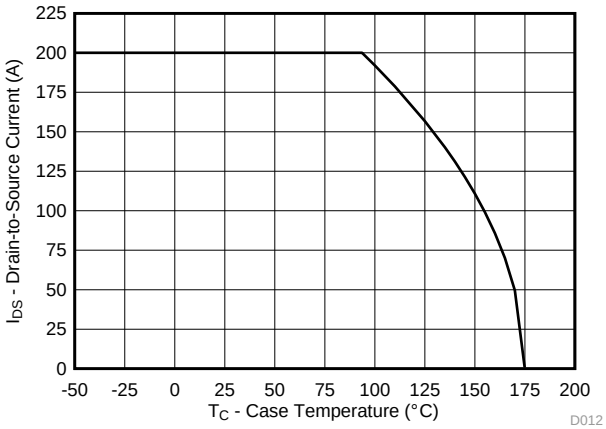

Figure 12. Maximum Drain Current vs Temperature

6 Device and Documentation Support

6.1 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

6.2 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E™ Online Community ***TI's Engineer-to-Engineer (E2E) Community.*** Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support ***TI's Design Support*** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

6.3 Trademarks

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6.4 Electrostatic Discharge Caution

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

6.5 Glossary

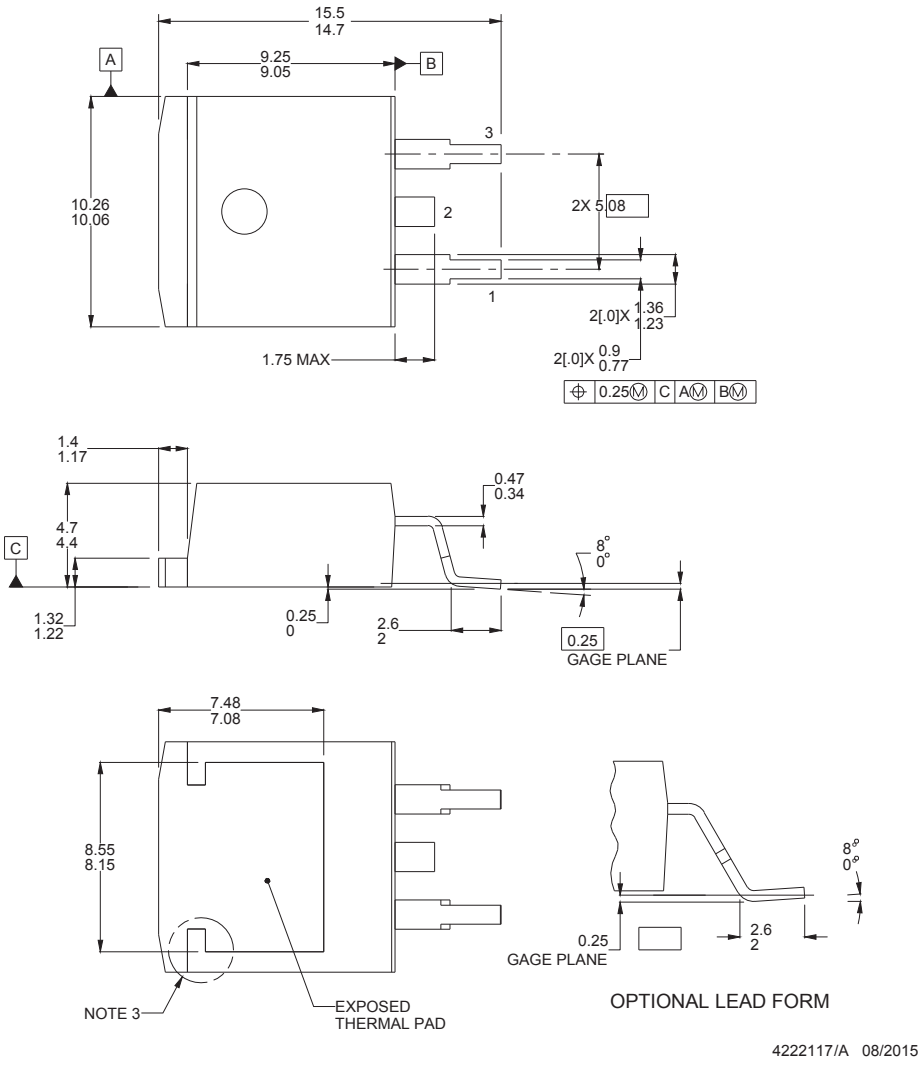
SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

7 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

7.1 KTT Package Dimensions



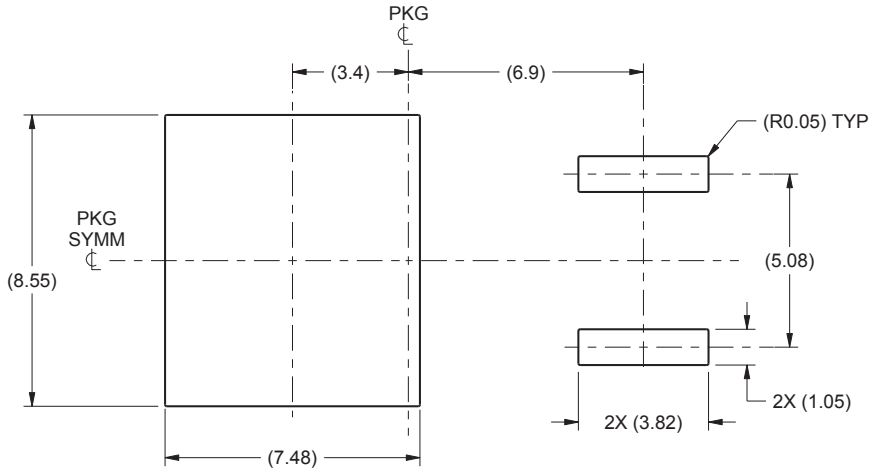
Notes:

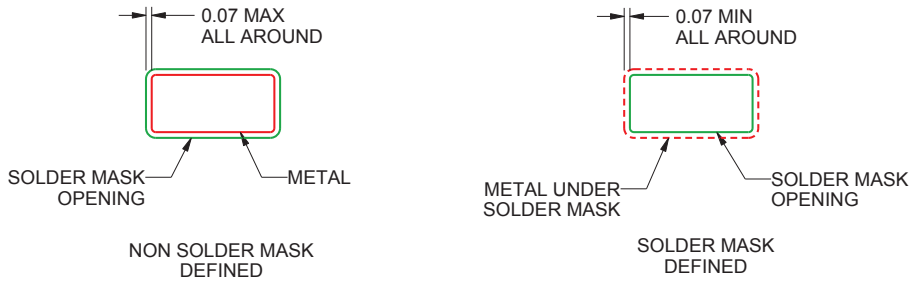
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Features may not exist and shape may vary per different assembly sites.

Table 1. Pin Configuration

POSITION	DESIGNATION
Pin 1	Gate
Pin 2 / Tab	Drain
Pin 3	Source

7.2 Recommended PCB Pattern



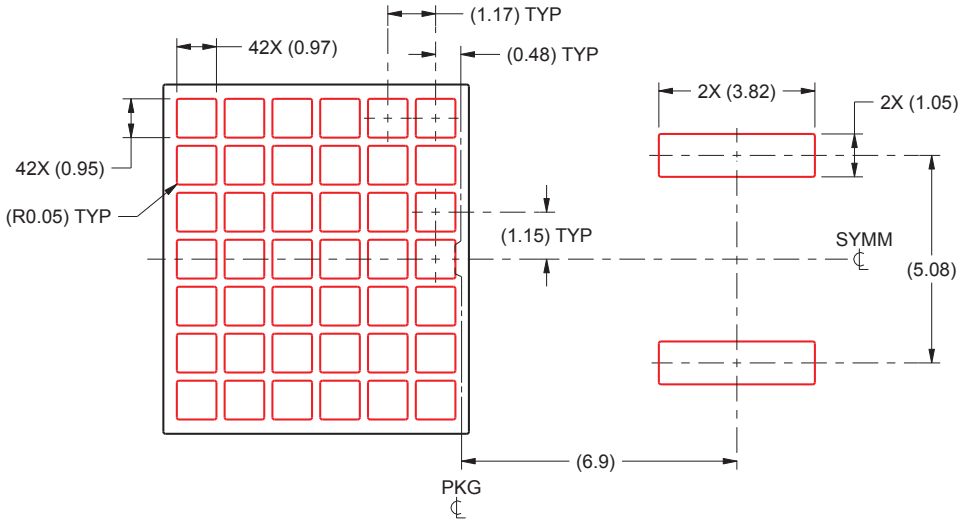


4222117/A 08/2015

Note:

1. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature numbers SLMA002 (www.ti.com/lit/slma002) and SLMA004 (www.ti.com/lit/slma004).

7.3 Recommended Stencil Opening



Notes:

1. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
2. Board assembly site may have different recommendations for stencil design.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
CSD19536KTT	ACTIVE	DDPAK/ TO-263	KTT	3	500	Pb-Free (RoHS Exempt)	CU SN	Level-2-260C-1 YEAR		CSD19536KTT	Samples
CSD19536KTTT	ACTIVE	DDPAK/ TO-263	KTT	3	50	Pb-Free (RoHS Exempt)	CU SN	Level-2-260C-1 YEAR		CSD19536KTT	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

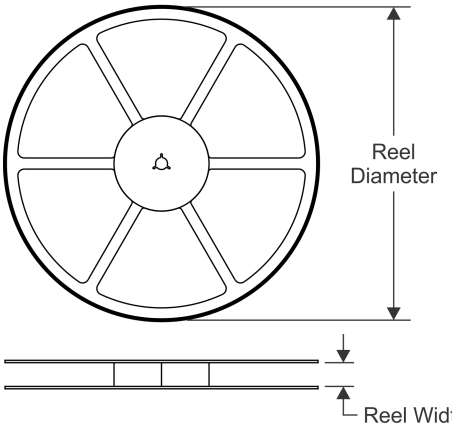
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

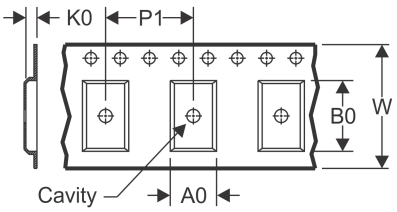
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

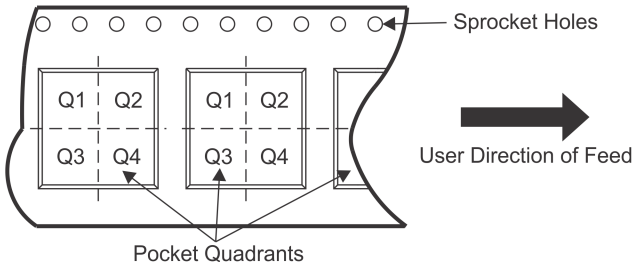


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

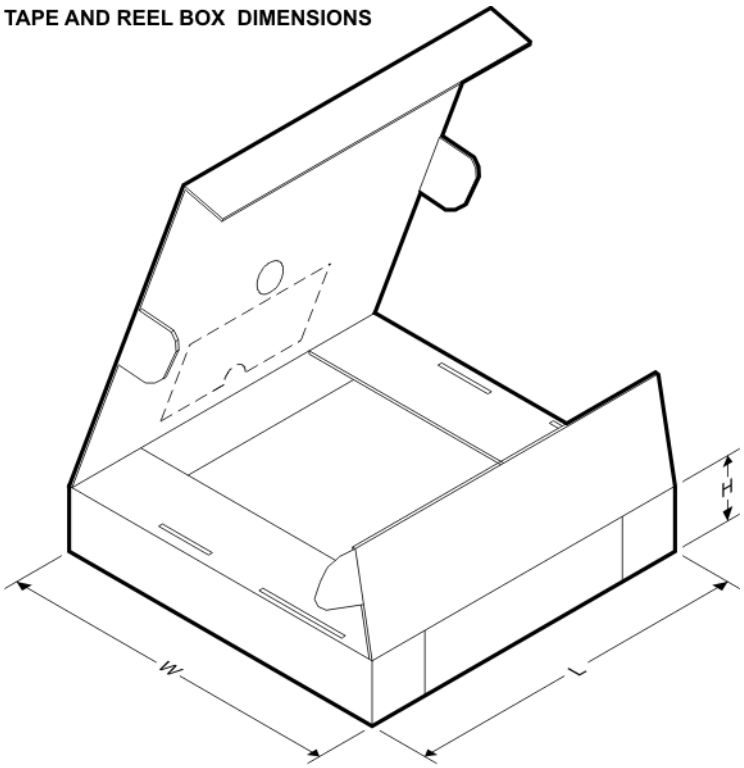
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CSD19536KTT	DDPAK/ TO-263	KTT	3	500	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2
CSD19536KTTT	DDPAK/ TO-263	KTT	3	50	330.0	24.4	10.8	16.3	5.11	16.0	24.0	Q2

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CSD19536KTT	DDPAK/TO-263	KTT	3	500	340.0	340.0	38.0
CSD19536KTTT	DDPAK/TO-263	KTT	3	50	340.0	340.0	38.0

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